US 20070069294A1

(19) United States
(12) Patent Application Publication
Chidambarrao et al.
(10) Pub. No.: US 2007/0069294 A1
(43) Pub. Date: Mar. 29, 2007

(54) STRESS ENGINEERING USING DUAL PAD NITRIDE WITH SELECTIVE SOI DEVICE ARCHITECTURE

(75) Inventors: **Dureseti Chidambarrao**, Weston, CT (US); **William K. Henson**, Poughkeepsie, NY (US); **Kern Rim**, Yorktown Heights, NY (US); **William C. Wille**, Red Hook, NY (US)

Correspondence Address:
SCULLY SCOTT MURPHY & PRESSER, PC
400 GARDEN CITY PLAZA
SUITE 300
GARDEN CITY, NY 11530 (US)

(73) Assignee: INTERNATIONAL BUSINESS MACHINES CORPORATION, Armonk, NY (US)

(21) Appl. No.: 11/162,953

(22) Filed: Sep. 29, 2005

Publication Classification

(51) Int. Cl.
H01L 27/12 (2006.01)
H01L 21/84 (2006.01)
(52) U.S. Cl. **257/351**; 438/153; 257/E29

(57) ABSTRACT

A method for engineering stress in the channels of MOS transistors of different conductivity using highly stressed nitride films in combination with selective semiconductor-on-insulator (SOI) device architecture is described. A method of using compressive and tensile nitride films in the shallow trench isolation (STI) process is described. High values of stress are achieved when the method is applied to a selective SOI architecture.

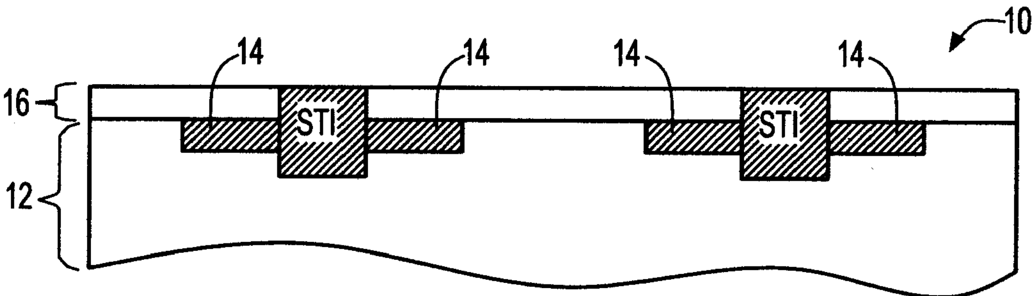

FIG. 1

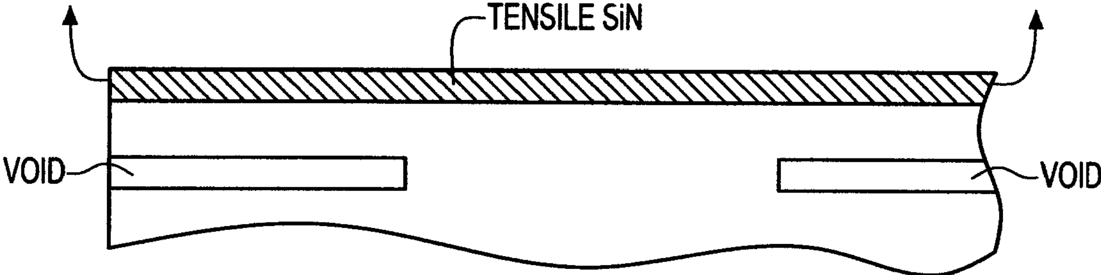

FIG. 2A

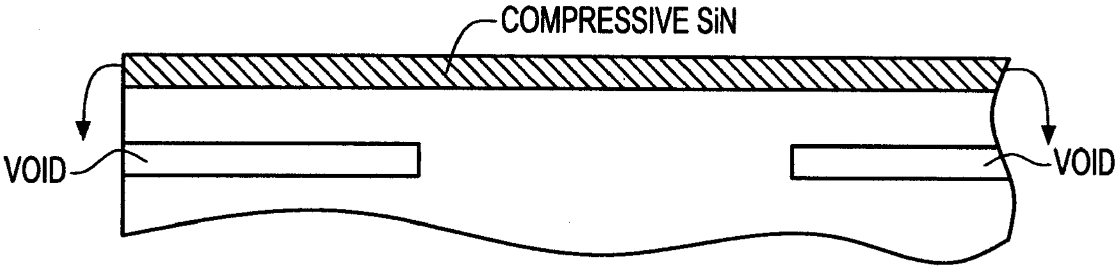

FIG. 2B

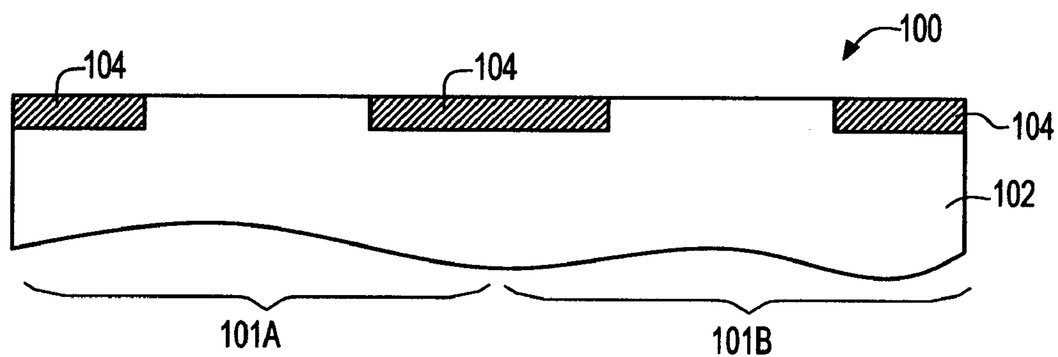

FIG. 3

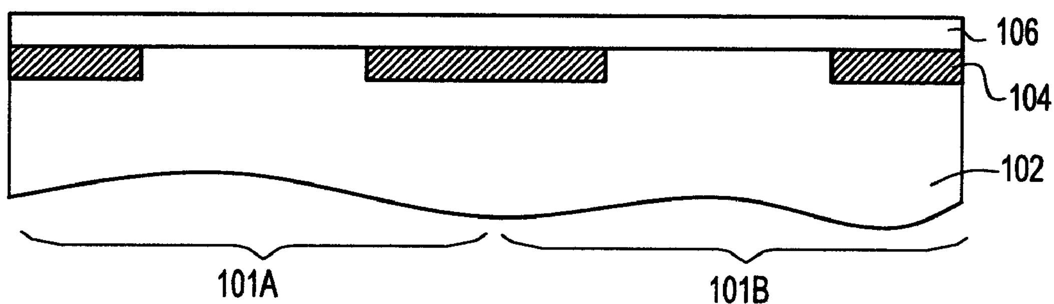

FIG. 4

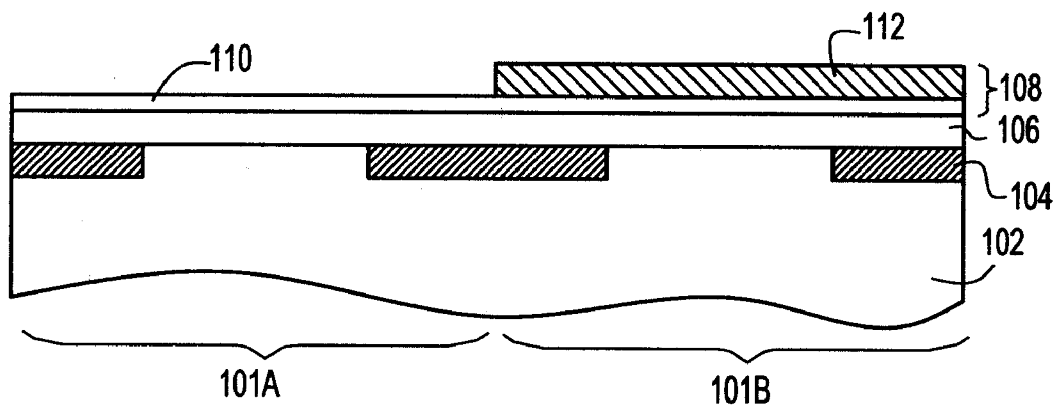

FIG. 5

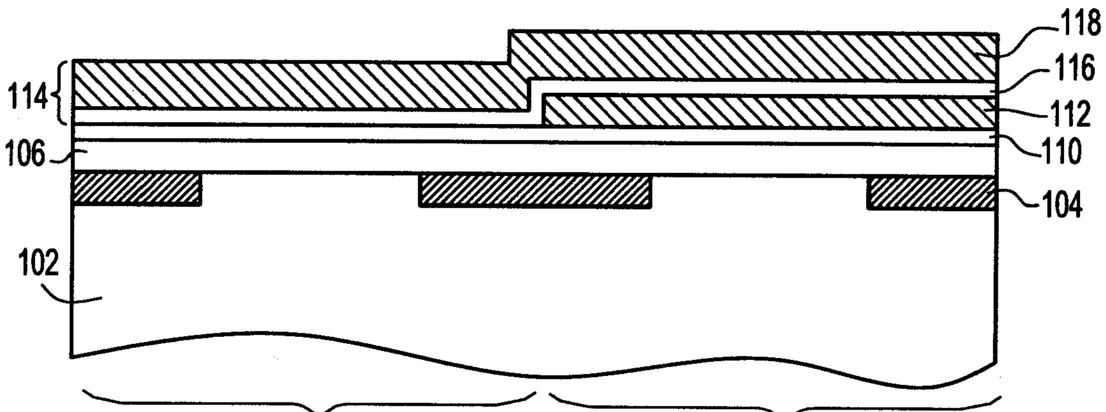

FIG. 6

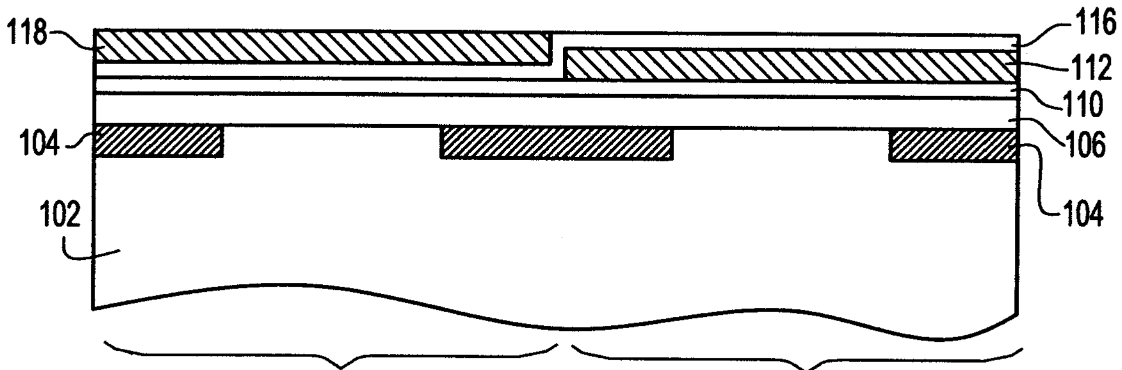

FIG. 7

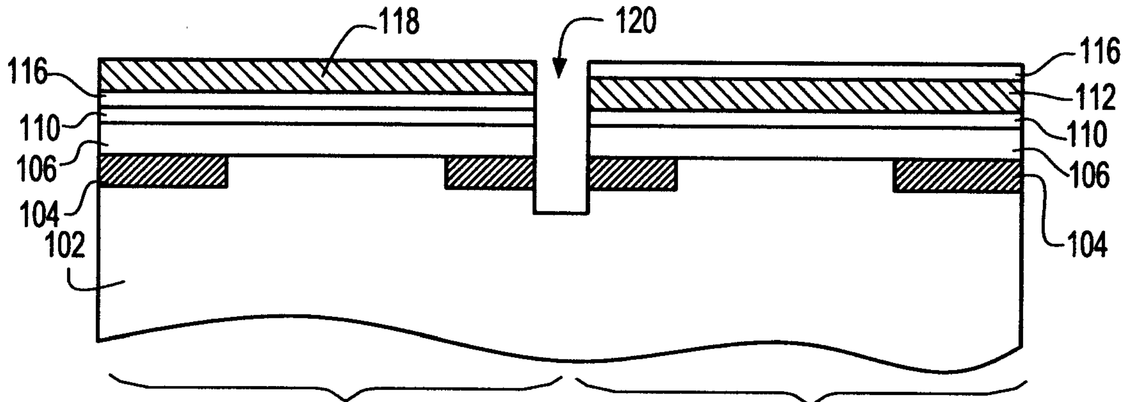

FIG. 8

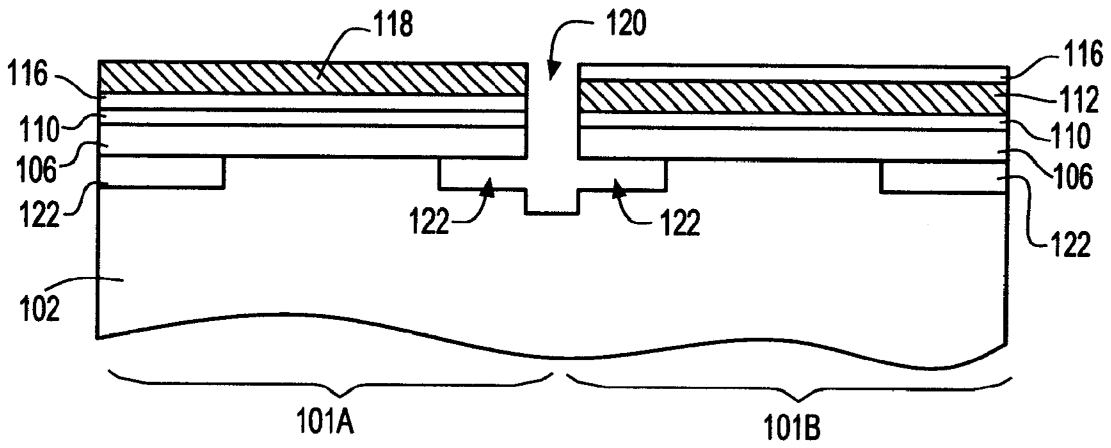

FIG. 9

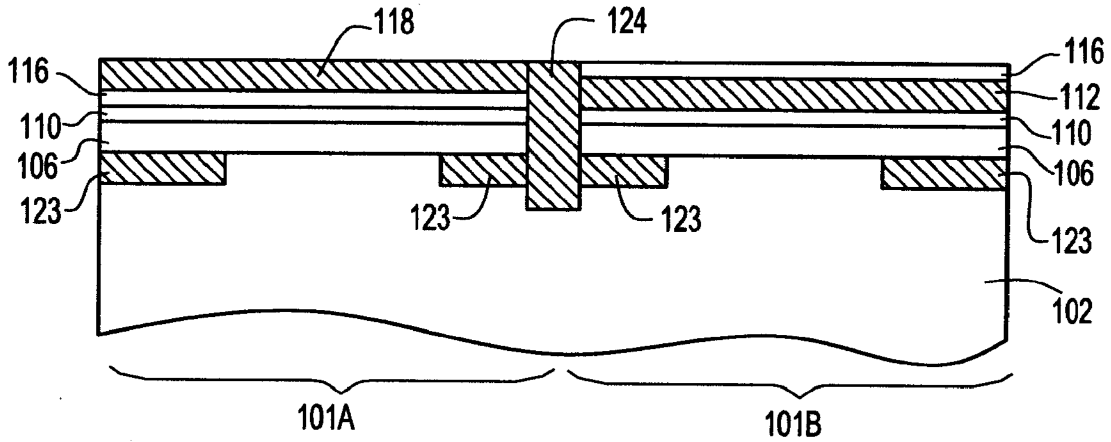

FIG. 10

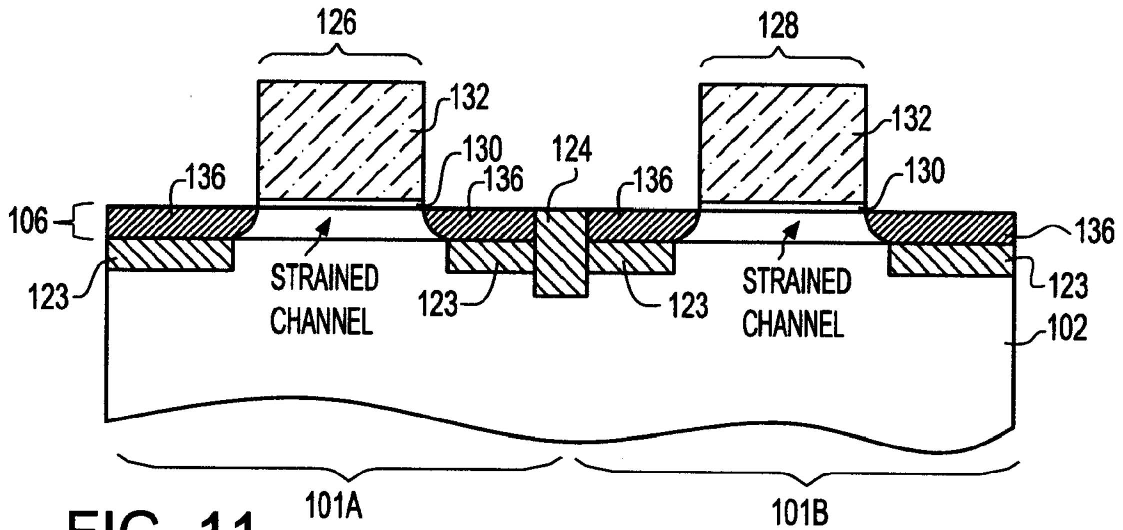

FIG. 11

STRESS ENGINEERING USING DUAL PAD NITRIDE WITH SELECTIVE SOI DEVICE ARCHITECTURE

FIELD OF THE INVENTION

[0001] The present invention relates to semiconductor device manufacturing, and more particularly to a method for engineering stress in channel regions of metal-oxide-semiconductor (MOS) devices of different conductivities using highly stressed nitride films in combination with a selective semiconductor-on-insulator (SOI) device architecture. Specifically, the inventive method uses compressive and tensile nitride films as the dual pad nitride in a shallow trench isolation (STI) process to induce stress in the channel regions of MOS transistors. High values of stress are achieved when the inventive method is applied to a selective SOI device architecture. The present invention also relates to the semiconductor structure that is manufactured utilizing the method of the present application.

BACKGROUND OF THE INVENTION

[0002] Conventional gate length and gate dielectric scaling of complementary metal oxide semiconductor (CMOS) technology no longer produces the desired improvements in device performance. Parasitic resistances and capacitances are becoming a fundamental limiting factor to improving device performance with each new technology node. New materials and device architectures are thus required in order to overcome these fundamental scaling obstacles that degrade device performance.

[0003] One approach to overcome these effects is to increase the drive current of the metal-oxide-semiconductor field effect transistor (MOSFET) by increasing the mobility of the carriers in the channel. It is well known that the application of mechanical stress can substantially improve or degrade the mobility of electrons and holes in a semiconductor; however, it is also known that electrons and holes respond differently to the same type of stress. For example, the application of compressive stress in the longitudinal direction of current flow is beneficial for hole mobility, but detrimental for electron mobility. The application of tensile stress in the longitudinal direction is beneficial for electrons, but detrimental for holes.

[0004] State of the art technology currently uses stress nitride liners that are deposited after silicidation to apply longitudinal stress to the channel and therefore increase the current drive of CMOS devices. However, it is imperative to develop an integration scheme that allows the desired application of stress (compressive or tensile) on the appropriate devices (nFETs or pFETs) to maximize performance of CMOS technology. Unfortunately, the use of stress liners appears to be approaching limitations in the magnitude of stress that can be applied to the channel of CMOS devices.

[0005] In view of the above, there is a need for providing an alternative method to achieve higher magnitudes of stress in the channel (and therefore higher mobility) with the desired type of stress (compressive for pFET and tensile for nFET).

SUMMARY OF THE INVENTION

[0006] The present invention provides a method for engineering stress in channel regions of MOS transistors of different conductivity using highly stressed nitride films in conjunction with a selective semiconductor-on-insulator (SOI) device architecture. More particularly, the present invention provides a method of using compressive and tensile nitride films as a dual pad nitride in a shallow trench isolation (STI) process. High values of stress are achieved when the method of the present invention is applied to a selective SOI device architecture. By "high values of stress" it is meant that stress values in the channel on the order of about 500 MPa or greater can be achieved utilizing the method of the present invention. More typically, the inventive method provides a stress range within the device channel from about 600 to about 700 MPa. The inventive method can be applied to a selective SOI device architecture that includes at least one nFET device region and at least one pFET device region.

[0007] In accordance with the present invention, high values of stress can be introduced into the channel regions of MOS devices utilizing the method of the present invention in which dual stress nitride films are employed as a pad nitride film in the MOS isolation process (e.g., STI process) in conjunction with a selective SOI device architecture. Dual stress nitride liner means that both tensile and compressive nitride films are deposited on the wafer covering the desired device regions (i.e., nFET region or pFET region). The use of the highly stressed nitride films as the pad nitride film of the isolation process does not incorporate much strain in a conventional bulk silicon wafer, which is why the selective SOI architecture is important.

[0008] The term "selective SOI architecture" is used herein to denote an SOI substrate including a top Si-containing semiconductor layer and a bottom Si-containing semiconductor layer, wherein portions of the top Si-containing semiconductor layer are separated from the Si-containing semiconductor layer by discrete buried oxide regions. In accordance with the present invention, the discrete buried oxides are present only beneath areas in which the source/drain junctions of the MOS device will eventually be present; no discrete buried oxide regions are present below the channel region of the MOS device.

[0009] A selective SOI architecture is formed by first providing a lateral void underneath the junctions of the device, which will maintain stress induced thereon and will be eventually filled with an oxide forming a buried oxide region of the structure. The lateral void underneath creates a free surface at the perimeter of the device. The free surface surrounding the perimeter of the device allows the Si-containing material at the surface to bend when a mechanical stress is applied. The tensile nitride film applies a lateral force that pulls the edges of the Si-containing material towards the center. As a result of the tensile force from the pad nitride, the Si-containing material bends up at the perimeter creating compressive strain in the center of the Si-containing channel. When compressive nitride is used as the pad nitride, the compressive nitride film applies a force in the opposite direction of the tensile film and as a result the Si-containing material bends down at the edges creating a tensile strain at the center of the Si-containing channel. Therefore a compressive pad nitride is used for nFET devices and a tensile pad nitride for the pFET devices in order to achieve the desired type of stress on nFETs and pFETs. In addition, the dual stress pad nitride must be applied on a substrate that subsequently will have a selective

SOI architecture in order to achieve the high levels of stress that are necessary for the desired increase in drive current.

[0010] In general terms, the method of the present invention comprises: providing a Si-containing structure having at least one first device region and at least one second device region, said structure including discrete n-doped regions therein;

forming a first material stack comprising a first pad oxide and a patterned first nitride film having a first stress, wherein said patterned nitride film is located over one of said device regions;

[0011] forming a second material stack comprising a second pad oxide and a patterned second nitride film having a second stress which is of a different stress type as the first stress, wherein said patterned second nitride film is located over one of said device regions not including said patterned first nitride film;

forming a trench into said first and second material stacks between said first and second device regions that extends down though at least one of said n-doped regions;

laterally etching said n-doped regions to create voids on each side of the trench which maintain stress of said overlying nitride films; and

filling said voids and trench with an oxide.

[0012] Following the filling step, the various layers of the first and stack material stacks can be removed from the structure and nFET and pFET devices can be formed. In accordance with the present invention, the pFETs are formed over a portion of the structure that is under compressive stress, whereas the nFETs are formed over a portion of the structure that is under tensile stress. The structure has a selective SOI architecture such that the junctions of the nFETs and pFETs are located above the filled voids, while the device channels are not.

[0013] In addition to the method described above, the present invention also provides a semiconductor structure that includes stress channel regions whose stress is within the ranges mentioned above. The semiconductor structure of the present invention comprises:

a selective SOI substrate including top and bottom Si-containing layers which are separated in predetermined regions by discrete buried oxide regions;

at least one nFET including source/drain diffusion regions and a tensile strained channel located on a portion of said substrate; and

[0014] at least one pFET including source/drain diffusion regions and a compressive strained channel located on other portions of said substrate, wherein said source/drain diffusion regions of said at least one nFET and said at least one pFET are located above said discrete buried oxide regions and said strained channels are not located above said discrete buried oxide regions.

BRIEF DESCRIPTION OF THE DRAWINGS

[0015] FIG. **1** is a pictorial representation (through a cross sectional view) depicting the selective SOI architecture utilized in the present invention.

[0016] FIGS. **2**A-**2**B are pictorial representations (through cross sectional views) depicting the selective SOI architecture with a tensile silicon nitride, SiN, layer (FIG. **2**A) and a compressive SiN layer (FIG. **2**B).

[0017] FIGS. **3**-**11** are pictorial representations (through cross sectional views) depicting the basic process steps of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

[0018] The present invention, which provides a method for engineering stress in the channel regions of MOS transistors of different conductivities as well as the structure formed utilizing the same, will now be described in greater detail by referring to the following description and drawings that accompany the present application. It is noted that the drawings of the present application are provided for illustrative purposes and, as such, they are not drawn to scale.

[0019] In accordance with the present invention, there are two key features that enable a large amount of stress to be applied to the channel of MOS devices: (1) the use of dual stress nitride films as the pad nitride in the STI isolation process and, (2) the dual nitride isolation process must be applied to a structure that will subsequently have a selective SOI device architecture. Dual stress nitride liner means that both tensile and compressive nitride films are deposited on the wafer covering the desired device regions (nFET or pFET). The use of the highly stressed nitride films as the pad nitride of the STI process does not incorporate much strain in the silicon on standard bulk silicon wafers which is why the selective SOI architecture is important. A selective SOI architecture allows the formation of a lateral void underneath the areas of the Si-containing material that will eventually include the S/D junctions of the device. The lateral void underneath creates a free surface at the perimeter of the device. The free surface surrounding the perimeter of the device allows the Si-containing material at the surface to bend when a mechanical stress is applied. These lateral voids, which extend from bottom edges of isolation trenches, maintain the stress induced by overlying stressed nitride layers. Moreover, these voids are subsequently filled with an oxide forming buried oxide regions of the selective SOI substrate. The oxide filled voids are in contact with oxide filled trench isolation regions.

[0020] FIG. **1** illustrates the selective SOI architecture used in the present invention. Specifically, the SOI architecture **10** comprises a top Si-containing semiconductor layer **16** and a bottom Si-containing semiconductor layer **12**, wherein portions of the top Si-containing semiconductor layer **16** are separated from the Si-containing semiconductor layer **12** by discrete buried oxide regions **14**. In accordance with the present invention, the discrete buried oxide regions **14** are present underneath areas of the top Si-containing semiconductor layer that will eventually receive the source/drain junctions of a MOS transistor. No discrete buried oxide is present underneath areas of the top Si-containing semiconductor layer in which the MOS channel will be present. The selective SOI architecture used in the present invention has been described previously in co-pending and co-assigned U.S. patent application Ser. Nos. 10/604,102, filed Jun. 26, 2003 and 10/754,320, filed Jan. 8, 2004, the entire contents of which are both incorporated herein by reference.

Note that FIG. **1** also shows the presence of trench isolation regions which are labeled as STI.

[**0021**] The term "Si-containing semiconductor" is used throughout the instant application to denote any semiconductor material that includes silicon. Illustrative examples of such Si-containing semiconductor materials include, but are not limited to: Si, SiGe, SiGeC, SiC, Si/Si, Si/SiC, Si/SiGe and Si/SiGeC. Preferably, both Si-containing layers **12** and **16** are comprised of Si. The Si-containing layers **12** and **16** may be doped or undoped.

[**0022**] The top Si-containing layer **16** of the SOI substrate **10** typically has a thickness from about 50 to about 200 nm, with a thickness from about 75 to about 100 nm being more typical. The thickness of the bottom Si-containing layer **12** is typically from about 500 to about 750 μm. The discrete buried oxide regions **14** can be a crystalline or non-crystalline oxide, which typically have a thickness from about 30 to about 100 nm.

[**0023**] FIG. **2**A illustrates how the Si-containing material bends when a film with high tensile stress (stress >1 GPa) is present on the surface. The tensile nitride film applies a lateral force that pulls the edges of the Si-containing material towards the center. As a result of the tensile force from the pad nitride, the Si-containing material bends up at the perimeter creating compressive strain in the center of the Si-containing material channel. FIG. **2**B illustrates the example when compressive nitride is used as the pad nitride. The compressive nitride film applies a force in the opposite direction of the tensile film and as a result the Si-containing material bends down at the edges creating a tensile strain at the center of the Si-containing material channel. Therefore a compressive pad nitride must be used for nFET devices and tensile pad nitride for the pFET devices in order to achieve the desired type of stress on nFETs and pFETs. In addition, the dual stress pad nitrides must be applied on a substrate, e.g., structure, that will eventually have a selective SOI architecture in order to achieve the high levels of stress that are necessary for the desired increase in drive current.

[**0024**] Reference is now made to FIGS. **3**-**11**, which illustrate in cross sectional view the basic processing steps of the present invention. Specifically, FIG. **3** illustrates an initial structure **100** that is employed in fabricating the inventive structure. As shown, the initial structure **100** includes a bulk Si-containing substrate **102** having n-doped regions **104** formed therein. The initial structure also includes a first device region **101**A and a second device region **101**B. The first device region **101**A is the area in which either an nFET or a pFET will be formed, while the second device area **101**B is the area in which the opposite conductivity type FET, as compared to the FET in the first device region, will be subsequently formed.

[**0025**] The n-doped regions **104** are areas in which the buried insulator **14** of the SOI substrate **10** will be subsequently formed. The n-doped regions **104** are typically formed at, or near, the upper surface of the bulk Si-containing substrate **100**. By "near" it is meant that the n-doped regions **104** have an upper surface that is within about 50 nm or less from the upper surface of the bulk Si-containing substrate **102**.

[**0026**] The n-doped regions **104** are formed utilizing a masked ion implantation process. Later in the process flow the n-doped regions **104** will be etched away selectively to the undoped regions forming voids; the voids will help to maintain stress induced by an overlying stressed nitride film and will be filled with an oxide forming discrete buried oxide regions of the selective SOI substrate. The implant species employed in forming the n-doped regions **104** are typically As, P or Sb. Implant energies used in forming the n-doped regions **104** typically range from about 5 keV to about 20 keV and ion doses from about 5E14 to about 2E15 atoms/cm^2 are typically used. Annealing may follow the implantation to cause activation and diffusion of the n-type dopants. The bulk Si-containing substrate **102** will become the bottom Si-containing layer **12** of the selective SOI substrate **10** shown in FIG. **1**.

[**0027**] FIG. **4** shows the structure after a Si-containing layer **106** is formed atop the initial structure **100**. The Si-containing layer **106**, which serves as the top Si-containing layer **16** of the selective SOI substrate **10** shown in FIG. **1**, is formed by an epitaxial growth process. The thickness of the Si-containing layer **106** may vary depending upon the desired thickness of the SOI layer and the depth of the source/drain junctions to be subsequently formed. Typically, the thickness of the Si-containing layer **106** is from about 5 to about 100 nm.

[**0028**] Next, a first material stack **108** comprising a first pad oxide **110** and a first nitride film **112** having a first stress (either tensile or compressive) is formed over the structure shown in FIG. **4**. In accordance with the present invention, the first pad oxide **110** is located underneath the first nitride film **112** on a surface of the Si-containing layer **106**. The first pad oxide **110** is formed by a conventional thermal oxidation process or by a conventional deposition process such as, for example, chemical vapor deposition, plasma enhanced chemical vapor deposition, evaporation, chemical solution deposition and atomic layer deposition. The first pad oxide **110** typically has a thickness from about 2 to about 10 nm. The first nitride film **112** having the first stress is formed utilizing a conventional deposition process such as, for example, chemical vapor deposition (CVD) or plasma enhanced chemical vapor deposition (PECVD). The thickness of the first nitride film **112** having the first stress is typically from about 30 to about 100 nm.

[**0029**] The first nitride film **112** having the first stress is then selectively etched away from one of the device areas such that the remaining first nitride film **112** is present in a device area which will have the greatest impact on the drive current of the MOS device to be subsequently formed therein. Thus, for example, if a tensile SiN film is used as film **112**, the selective etching process removes the tensile SiN film from the device region(s) where nFET devices will be subsequently formed. If a compressive film is used as film **112**, the compressive SiN film is selectively removed from the device region(s) where pFET devices will be subsequently formed. The selectively etching is achieved by first applying a photoresist to the upper surface of film **112**, and then forming a pattern into the photoresist utilizing a conventional photolithography process (i.e., exposing the photoresist to a pattern of radiation and developing the exposed photoresist utilizing a conventional resist developer). After photolithograpy, an etching process that removes nitride selective to oxide is performed. The etching process may include any dry etching technique such as, reactive-ion etching, plasma etching, ion beam etching or laser ablation.

Alternatively, a wet etch technique utilizing a chemical etchant can also be used. The resultant structure, in one embodiment of the present invention, including the patterned first nitride film **112** atop the unpatterned pad oxide **110** is shown in FIG. **5**. Although the patterned first nitride film **112** is shown over the second device region **101**B, the present invention also contemplates the case when the patterned first nitride film **112** is located only over the first device region **101**A.

[**0030**] Next, a second material layer **114** including a second pad oxide **116** and a second nitride film **118** having a second stress that is of a different stress type than the first nitride film **112** is formed on the structure shown in FIG. **5**. The second pad oxide **116** forms atop exposed surfaces of the first pad oxide **110** and the patterned nitride film **112**. The second pad oxide **116** is used to protect the first nitride film **112** during the subsequent patterning of the second nitride film **118**. The processing and thickness of the second pad oxide **116** and the second nitride film **118** are similar to those reported above for the first pad oxide **110** and the first nitride film **112**. The structure including the second material layer **114** is shown in FIG. **6**.

[**0031**] The structure illustrated in FIG. **6** is then patterned (as described above) to remove the second nitride film **118** from the area of the structure that previously included the first nitride film **112**. This structure is shown in FIG. **7**. As shown, the first device region **101**A includes, for example, only the second nitride film **118**, while the second device region **101**B includes only the first nitride film **112**. The location of the first and second nitride films can be switched depending on the type of device which will be subsequently formed in the specific area. In one embodiment, the first device region **101**A is an nFET device region which is covered with a compressive nitride film **118**, while the second device region **101**B is a pFET device region that is covered with a tensile nitride film **112**. In another embodiment, the first device region **101**A is a pFET device region which is covered with a tensile nitride film **118**, while the second device region **101**B is an nFET device region that is covered with a compressive nitride film **112**. It is again emphasized that the compressive film causes a channel to be under tensile strain, whereas a tensile film causes a channel to be under compressive strain.

[**0032**] FIG. **8** shows the structure after forming at least one trench opening **120** into the structure shown in FIG. **7**. As shown, the trench opening **120** is formed between the first and second device regions (**101**A and **101**B, respectively) extending down and through at least one of the non-doped regions **104**. The trench opening **120** is formed by lithography and etching. The etching process may comprise a single etch (wet or dry) or a combination thereof.

[**0033**] FIG. **9** shows the structure that is formed after performing a lateral etching process which is capable of removing the n-doped regions **104** from the structure forming voids **122** in the Si-containing material. This step is critical for creating stress in the Si-containing material located above the voids. The lateral etch is performed utilizing any etching process that is selective in removing the n-doped regions **104** as compared with the undoped semiconductor regions. For example, a dry etch in chlorine, i.e., Cl_2, can be used in this step of the present invention.

[**0034**] It is noted that after the lateral etch, the Si-containing material near the surface is free to bend due to force applied from the tensile and compressive silicon nitride films, as described above in connection with FIGS. **2**A and **2**B. As a result, the Si-containing material in the channel region is highly strained (i.e., the Si-containing material under the tensile strained silicon nitride film is under compressive strain, while the Si-containing material under the compressively strained silicon nitride film is under tensile strain).

[**0035**] Next, and as shown in FIG. **10**, the at least one trench opening **120** and the voids **122** created by the lateral etching process mentioned above are filled with an oxide utilizing a conventional deposition process such as, for example, plasma-assisted chemical vapor deposition. Note that the oxide filled voids **123**, which are connected to trench isolation regions **124**, form the discrete and buried oxide regions **14** shown in FIG. **1**. After deposition, a planarization process such as, for example, chemical mechanical polishing (CMP) and/or grinding is used to complete the formation of trench isolation regions **124**. One key aspect to mention is than the strain in the Si-containing channels created by the nitride films will be retained in the Si-containing material because of the oxide fill.

[**0036**] The structure shown in FIG. **10** is then subjected to another planarization process which removes any remaining pad oxide and nitride films from the structure and thereafter MOS devices are formed on the surface of the planarized structure utilizing a conventional CMOS process. This step of the present invention provides the structure illustrated in FIG. **11** wherein a first FET **126** of a first conductivity type is formed in the first device region **101**A and a second FET **128** of a second conductivity type that is different from the first conductivity type is formed in the second device region **101**B. Specifically, an nFET is formed in the region that is under tensile strain, while a pFET is formed in the region under compressive strain.

[**0037**] As stated above, the FETs are formed utilizing conventional complementary metal oxide semiconductor (CMOS) processing steps that are well known to those skilled in the art. For example, each FET can be formed by first forming a layer of gate dielectric **130** on an upper surface of the top Si-containing layer of the SOI substrate. The term "gate dielectric" is used in the present invention to denote any insulating material, such as an oxide, nitride or oxynitride, that is typically employed as the gate dielectric of an MOSFET. The gate dielectric **130** is formed by a conventional deposition process such as, for example, chemical vapor deposition (CVD), plasma-assisted CVD, atomic layer deposition, physical vapor deposition or another like deposition process. Alternatively, the gate dielectric **130** can be formed by a thermal oxidation, nitridation or oxynitridation process. The thickness of the gate dielectric **130** is typically from about 1 to about 10 nm.

[**0038**] After formation of the gate dielectric, a gate conductor **132** is formed atop the gate dielectric. The gate conductor **132** may include any conductive material, including for example, doped polysilicon, conductive elemental metals, alloys of conductive elemental metals, suicides of conductive elemental metals, nitrides of conductive elemental metals, or any combination thereof. A diffusion barrier and/or a dielectric cap may be formed within or atop the gate conductor **132**. Gate conductor **132** can be formed by a conventional deposition process such as, for example, CVD,

plasma-assisted CVD, evaporation, sputtering, plating or another like deposition process. When polysilicon is employed, the polysilicon gate conductor is a doped material that can be formed in-situ, or by deposition and then ion implantation. The thickness of the gate conductor **132** is typically from about 100 to about 300 nm.

[**0039**] It is noted that the gate dielectric and the gate conductor of the FETs of different conductivities may be comprised of the same materials, or different gate dielectrics and/or gate conductors may be used.

[**0040**] Following formation of the gate conductor, the gate conductor and typically, the gate dielectric are patterned by lithography and etching. Next, insulating spacers (not shown) are typically formed (by deposition and etching) on the exposed sidewalls of at least the patterned gate conductor. Following spacer formation, the source/drain diffusion regions **134** are formed into the top Si-containing layer of the SOI substrate by ion implantation and annealing. As shown, the source/drain regions **134** are located above the oxide filled void regions (e.g., the buried oxide regions) of the SOI structure.

[**0041**] The annealing causes diffusion of the implanted dopants. The extent of the diffusion determines the length of the channel regions in the top Si-containing layer of the SOI substrate. The channel regions **136** are positioned such that no buried oxide is positioned there below.

[**0042**] It should be emphasized that the channel regions **136** are stressed without the need of using a conventional stress liner and/or embedded stress regions. As stated above, high stressed channel are formed into the Si-containing material by providing lateral voids in a structure that includes dual stress nitride pad films. These pad films, which are used in forming the STI region are removed from the structure and then CMOS devices are formed thereon.

[**0043**] While the invention has been described herein with reference to specific embodiments, features and aspects, it will be recognized that the invention is not thus limited, but rather extends in utility to other modifications, variations, applications, and embodiments, and accordingly all such other modifications, variations, applications, and embodiments are to be regarded as being within the spirit and scope of the invention.

1. A semiconductor structure comprising:

a selective SOI substrate including top and bottom Si-containing layers which are separated in predetermined regions by discrete buried oxide regions;

at least one nFET including source/drain diffusion regions and a tensile strained channel located on a portion of said substrate; and

at least one pFET including source/drain diffusion regions and a compressive strained channel located on other portions of said substrate, wherein said source/drain diffusion regions of said at least one nFET and said at least one pFET are located above said discrete buried oxide regions, said strained channels are not located above said discrete buried oxide regions, and said strained channels have a stress value of about 500 MPa or greater.

2. The semiconductor structure of claim 1 wherein said top Si-containing layer comprises an epi Si-containing layer.

3. The semiconductor structure of claim 1 wherein said bottom Si-containing layer is a bulk Si-containing material.

4. The semiconductor structure of claim 1 wherein said discrete buried oxide regions have a thickness from about 30 to about 100 nm.

5. The semiconductor structure of claim 1 wherein said discrete buried oxide regions extend from bottom edges of oxide filled trench isolation regions.

6. The semiconductor structure of claim 1 wherein said at least one pFET and said at least one nFET each include a gate dielectric and a gate conductor.

7. The semiconductor structure of claim 6 wherein said gate dielectric comprises an insulating oxide, nitride or oxynitride.

8. The semiconductor structure of claim 6 wherein said gate conductor comprises doped polysilicon, a conductive elemental metal an alloy of a conductive elemental metal, a silicide of a conductive elemental metal, a nitride of a conductive elemental metal or combinations thereof.

9. (canceled)

10. The semiconductor structure of claim 1 wherein said stress value is from about 600 to about 700 MPa.

11. The semiconductor structure of claim 1 wherein said stress value is obtained without overlying stress nitride films being present about said at least one nFET or said at least one pFET.

12. A method of fabricating a semiconductor structure comprising:

providing a Si-containing structure having at least one first device region and at least one second device region, said structure including discrete n-doped regions therein;

forming a first material stack comprising a first pad oxide and a patterned first nitride film having a first stress, wherein said patterned nitride film is located over one of said device regions;

forming a second material stack comprising a second pad oxide and a patterned second nitride film having a second stress which is of a different stress type as the first stress, wherein said patterned second nitride film is located over one of said device regions not including said patterned first nitride film;

forming a trench into said first and second material stacks between said first and second device regions which extends down though at least one of said n-doped regions;

laterally etching said n-doped regions to create voids on each side of the trench which maintain stress of said overlying nitride films; and

filling said voids and trench with an oxide.

13. The method of claim 12 wherein said forming said Si-containing structure comprises implanting said n-doped regions into a bulk Si-containing substrate at or near a surface thereof, and forming an epi Si-containing layer on said bulk Si-containing substrate.

14. The method of claim 13 wherein said implanting comprises a masked ion implantation process wherein As, P or Sb are used as an n-type dopant.

15. The method of claim 13 wherein said implanting is performed at an energy from about 5 to about 20 keV and ion doses from about 5E14 to about 2E15 atoms/cm2 are used.

16. The method of claim 12 wherein n-doped regions are located at or near a surface of a bulk Si-containing substrate.

17. The method of claim 1 wherein said patterned first nitride film is located in a device region where nFETs are to be built, said patterned first nitride film having compressive strain, and patterned second nitride film is located in a device region where pFETs are to be built, said patterned second nitride film having tensile strain.

18. The method of claim 17 further comprising removing said first and second material stacks from said Si-containing structure and forming at least one pFET and at least one nFET, wherein said at least one pFET is formed in areas including said patterned second nitride film and said at least one nFET is formed in areas including said patterned first nitride film.

19. The method of claim 12 wherein said patterned first nitride film is located in a device region where pFETs are built, said patterned first nitride film having tensile strain, and patterned second nitride film is located in a device region where nFETs are to be built, said patterned second nitride film having compressive strain.

20. The method of claim 19 further comprising removing said first and second material stacks from said Si-containing structure and forming at least one pFET and at least one nFET, wherein said at least one pFET is formed in areas including said patterned first nitride film and said at least one nFET is formed in areas including said patterned second nitride film.

* * * * *